

Sub 1
electromagnetic interference suppressing body during use thereof in association with said electronic device.

Sub 2
11. (Amended) The electronic device of claim 10, wherein said heat conductive powder is at least one selected from the group consisting of alumina (Al_2O_3), aluminum nitride (AlN), cubic boron nitride (BN) and silicon carbide (SiC).

12. (Amendment) The electronic device of claim 11, wherein said organic binding agent is a thermoplastic resin having a glass transition temperature of not less than about 120°C .

Sub 3
13. (Amended) The electronic device of claim 12, wherein said organic binding agent is at least one of thermoplastic polyamide and a liquid crystal polymer.

Sub 4
14. (Amended) The electronic device of claim 13, wherein said electromagnetic interference suppressing article is in the form of a sheet, for use in contact with components to control the temperature thereof during use of said electronic device.

Sub 5
Please add the following claims. (NE)

Sub 6
-- 15. A combination of an electronic device, susceptible to and/or generating magnetic waves, and having adjacent thereto an electromagnetic interference suppressing

article, said article comprising:

13 a first composite magnetic body, comprising a first soft magnetic powder and a first heat conductive powder dispersed through a first organic binding agent; and
an electrically conductive support, mounted on said first composite magnetic body.--

-- 16. The electronic device of claim 15, further comprising a second composite magnetic body, mounted on said electrically conductive support, comprising a second soft magnetic powder and second heat conductive powder dispersed through a second organic binding agent.--

17. The electronic device of claim 15 or 16, wherein said electrically conductive support is at least one selected from the group consisting of a textile of electrically conductive fiber, an electric conductor plate, an electric conductor mesh plate, a textile of soft magnetic metal fiber, a soft magnetic metal plate, and a soft magnetic metal mesh plate.--

-- 18. The electronic device of claim 15 or 16, further comprising a heat sink mounted on the electromagnetic interference suppressing article.--

-- 19. The electronic device of claim 15, further comprising electrical components,

wherein said first composite magnetic body is mounted on said electrical components.--

Sub 7
12 -- 20. The electronic device of claim 16, wherein said electrical components are in the form of an integrated circuit.--

-- 21. The electronic device of claim 20, wherein said integrated circuit is mounted on a circuit board.--

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cont'd -- 22. A method for suppressing magnetic waves comprising the steps of:

providing a first composite magnetic body, comprising a soft magnetic powder and a heat conductive powder dispersed in an organic binding agent;

attaching an electrically conductive support on said first composite magnetic body;

providing an electronic device, susceptible to and/or generating magnetic waves; and

positioning said first composite magnetic body adjacent to said electronic device.--

-- 23. The method of claim 21, further comprising the step of mounting a second composite magnetic body on said electrically conductive support.--

-- 24. The method of claim 21, wherein said electrically conductive support is at least one selected from the group consisting of a textile of electrically conductive fiber, an electric conductor plate, an electric conductor mesh plate, a textile of soft magnetic metal fiber, a soft magnetic metal plate, and a soft magnetic metal mesh plate.--

-- 25. The method of claim 22, further comprising a heat sink mounted on said electrically conductive support or said second composite magnetic body.--

*OLD
cancel* -- 26. The method of claim 21, wherein said first composite magnetic body is mounted on an electronic device, susceptible to and/or generating magnetic waves.--

-- 27. The method of claim 21, wherein said first composite magnetic body is mounted on an integrated circuit.--